

June 1997

COMPLETE DATA SHEET COMING SOON!

CD54AC574/3A CD54ACT574/3A

Octal D-Type Flip-Flop, Three-State Positive-Edge Triggered, Non-Inverting

Description

The CD54AC574/3A and CD54ACT574/3A are octal D-type, three-state, positive-edge triggered flip-flops that utilize the Harris Advanced CMOS Logic technology. The eight flip-flops enter data into their registers on the LOW-to-HIGH transition of the clock (CP). The Output Enable (\overline{OE}) controls the three-state outputs and is independent of the register operation. When the Output Enable (\overline{OE}) is HIGH, the outputs are in the high-impedance state. The CD54AC574/3A and CD54ACT574/3A are non-inverted.

The CD54AC574/3A and CD54ACT574/3A are supplied in 20 lead dual-in-line ceramic packages (F suffix).

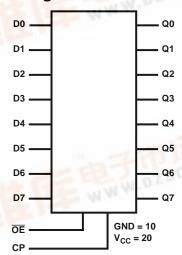
ACT INPUT LOAD TABLE

| INPUT | UNIT LOAD (NOTE 1) | |
|------------------|--------------------|--|
| D, OE | 0.7 | |
| СР | | |

NOTE:

 Unit load is ΔI_{CC} limit specified in DC Electrical Specifications Table, e.g., 2.4mA Max at +25°C.

Functional Diagram



Absolute Maximum Ratings

| DC Supply Voltage, V _{CC} 0.5V to +6\ | V |
|------------------------------------------------------------------------|---|
| DC Input Diode Current, I _{IK} | |
| For $V_1 < -0.5V$ or $V_1 > V_{CC} + 0.5V$ ±20m/ | Α |
| DC Output Diode Current, I _{OK} | |
| For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$ | Α |
| DC Output Source or Sink Current, Per Output Pin, IO | |
| For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$ | Α |
| DC V _{CC} or GND Current, I _{CC} or I _{GND} | |
| For Up to 4 Outputs Per Device, Add ±25mA For Each | |
| Additional Output±100m/ | Α |
| | |
| | |

| Power Dissipation Per Package, P _D |
|---------------------------------------------------------------|
| $T_A = -55^{\circ}C$ to $+100^{\circ}C$ (Package F) 500mW |
| $T_A = +100$ °C to +125°C (Package F) Derate Linearly at |
| 8mW/°C to 300mW |
| Operating Temperature Range, T _A |
| Package Type F55°C to +125°C |
| Storage Temperature, T _{STG} 65°C to +150°C |
| Lead Temperature (During Soldering) |
| At Distance 1/16in. ± 1/32in. (1.59mm ± 0.79mm) |
| From Case For 10s Max+265°C |
| Unit Inserted Into a PC Board (Min Thickness 1/16in., 1.59mm) |
| With Solder Contacting Lead Tips Only +300°C |
| |

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Recommended Operating Conditions

| Operating Temperature, T _A | -55°C to +125°C |
|---------------------------------------|-----------------|
| Input Rise and Fall Slew Rate, dt/dv | |
| at 1.5V to 3V (AC Types) | 0ns/V to 50ns/V |
| at 3.6V to 5.5V (AC Types) | 0ns/V to 20ns/V |
| at 4.5V to 5.5V (AC Types) | 0ns/V to 10ns/V |

